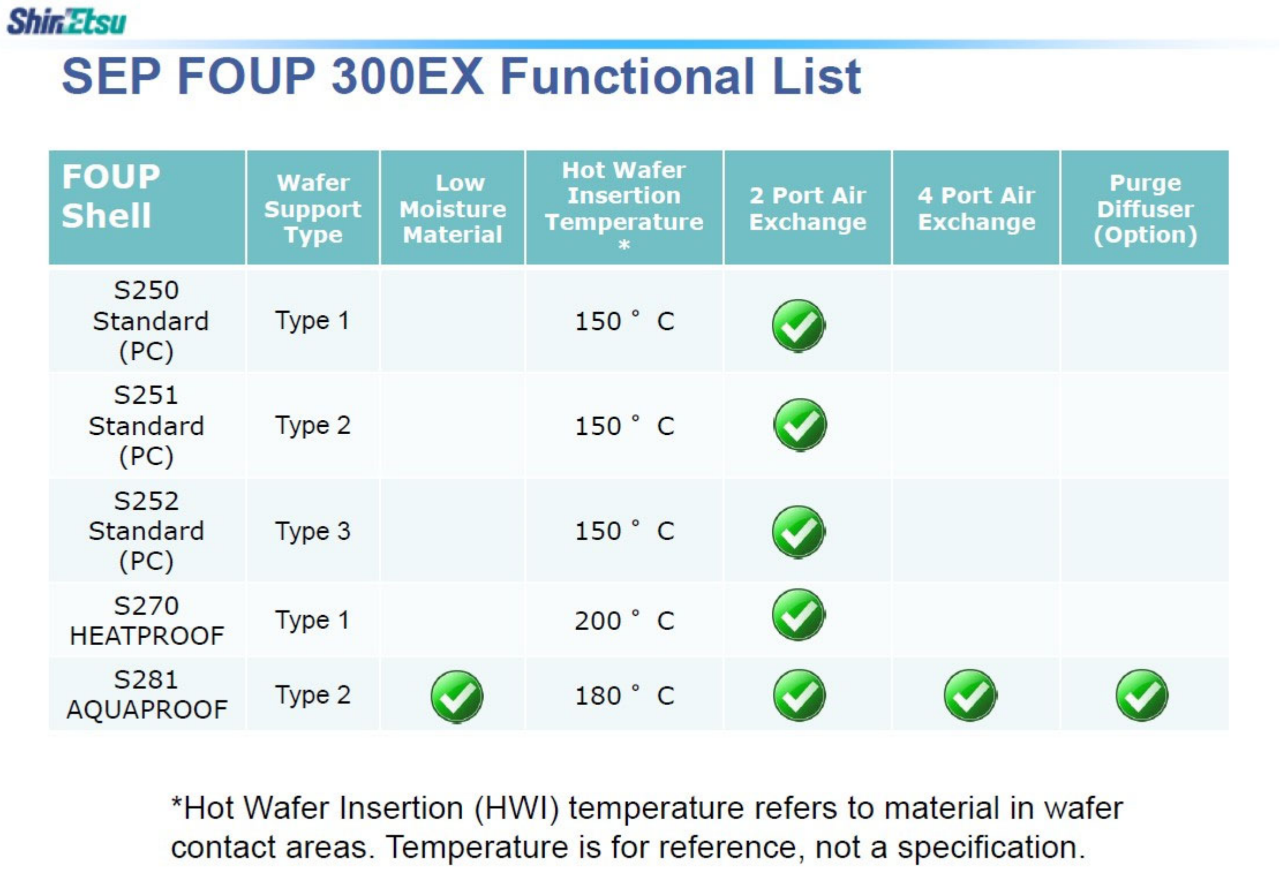
Shin Etsu 300EX S281 Aquaproof FOUP Wafer Shipping Boxes (JAD-38285)

Make:	**Shin Etsu**
Model:	**300EX S281 Aquaproof**
Quantity:	**100+ Available. Please Inquire for Large Order**
Condition:	**Great Condition but previously used with Copper Wafers**

Configuration:

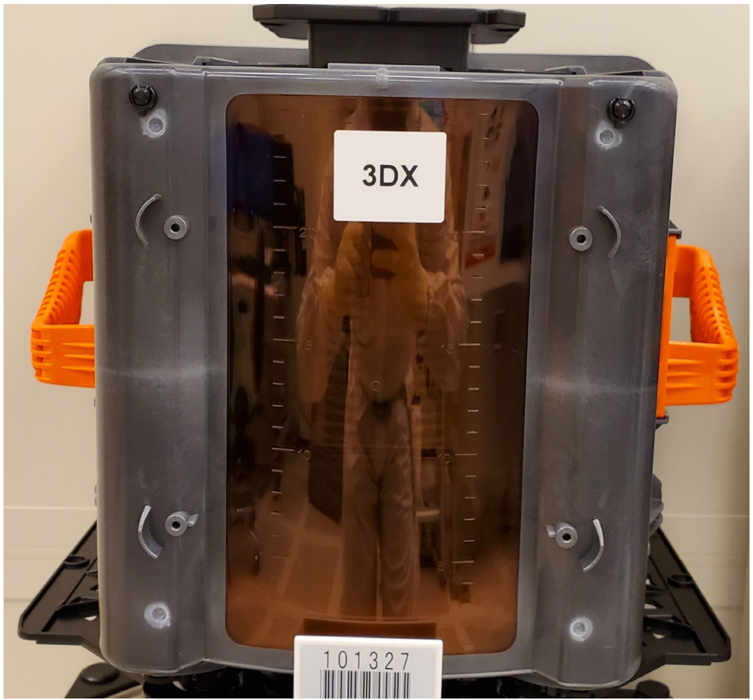


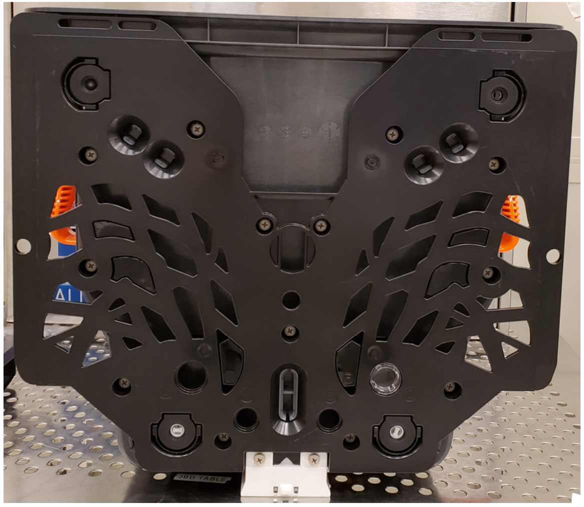
ShinEtsu

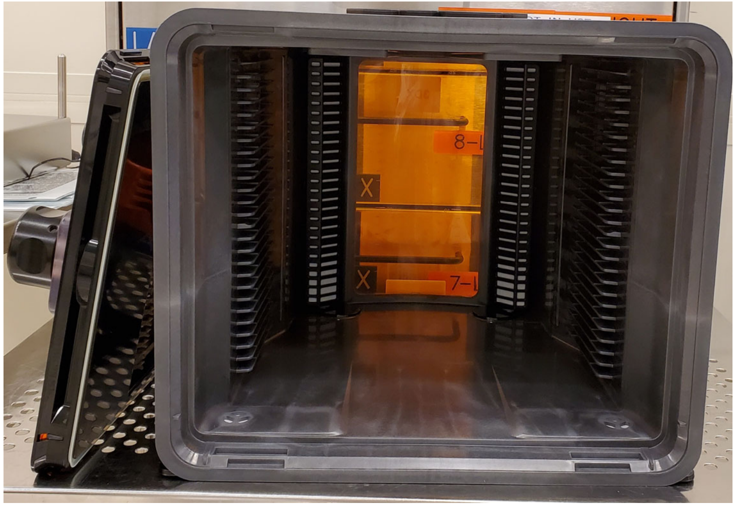
SEP FOUP 300EX Functional List

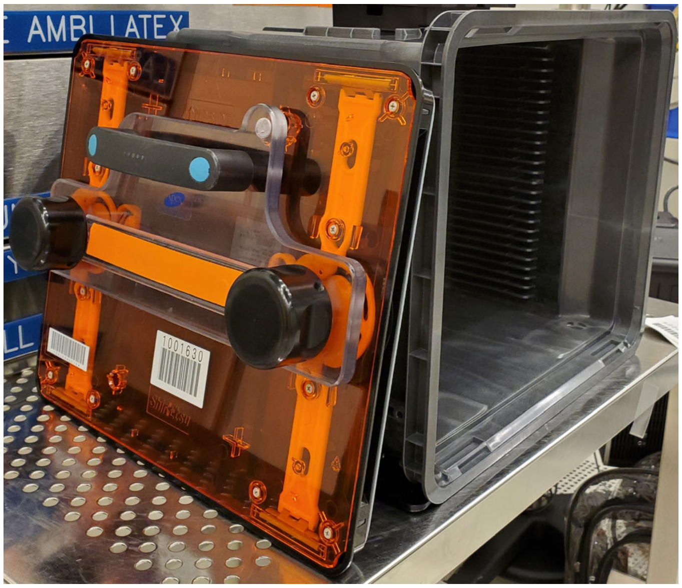
FOUP Shell	Wafer Support Type	Low Moisture Material	Hot Wafer Insertion Temperature *	2 Port Air Exchange	4 Port Air Exchange	Purge Diffuser (Option)
S250 Standard (PC)	Type 1		150 ° C	✓		
S251 Standard (PC)	Type 2		150 ° C	✓		
S252 Standard (PC)	Type 3		150 ° C	✓		
S270 HEATPROOF	Type 1		200 ° C	✓		
S281 AQUAPROOF	Type 2	✓	180 ° C	✓	✓	✓

*Hot Wafer Insertion (HWI) temperature refers to material in wafer contact areas. Temperature is for reference, not a specification.









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